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TUCSON, Ariz. - May 15, 2000 - Brush Wellman Inc (NYSE:BW), Powder Metal Products Group (a business unit of the Electronic Products Division) today announced that the United States Patent Office has awarded a patent to manufacture improved net shape or near net shape copper/tungsten products. Inventors of the process are David Jech, Director of Technology, Juan Sepulveda, Director of Technical Marketing, and Anthony Traversone, Process Engineering Specialist, all of Powder Metal Products Group.

Net shape or near net shape parts are improved by sintering a metal containing chemically bound oxygen compact in a well controlled moisture containing hydrogen atmosphere. Densification is aided by the formation of a transient metal-metal oxide eutectic during the sintering.

"The new process offers greater efficiency and lower cost manufacturing of iron, copper and nickel based P/M parts by eliminating the post-fired machining step" stated Ralph Hershberger, General Manager, Powder Metal Products Group.

Copper/tungsten applications include microprocessors, microwave modules, wireless telecommunication devices and other power RF packages.

Brush Wellman Inc., Electronic Products Division, with headquarters in Cleveland, Ohio, is a manufacturer of engineered materials. The Company and its subsidiaries supply worldwide markets with Beryllium Products, Alloy Products, Electronic Products, Precious Metal Products and Engineered Material Systems.